

2023/10

ADEKA REMYLOP FL-502

Product Features

- One-component heat curing adhesive
- Rapid curing type
- Semi-after cureless
- Epoxy type (Halogen-free available)
- NIR laser curable

Properties (uncured)

Viscosity / 25°C	2 ⁻¹	44	Pa · s
	20 ⁻¹	19	Pa · s
Thixotropic value	2 ⁻¹ /20 ⁻¹	2.4	
Specific gravity		1.15	
Filler content		0	wt %
Nonvolatile content		> 99	%
Pot Life	25 °C	> 24	hrs
Shelf Life	≤ -20 °C	> 180	days

Cured Material Properties

Glass transition temperature	TMA	120	°C
	DMA	153	°C
Hardness	ShoreD	>	
		D80	
Storage modulus/ 25°C	DMA	2.6	GPa
Coefficient of linear expansion	α1	65	ppm
	α2	190	ppm
Thermal conductivity	Transient hot wire method	0.3	W/m · K
Curing shrinkage	Densitometry method	2.5	%

DSC : SII DCS6220 25 – 250 °C (10 °C/min)

DMA : TA RSA-G2 -50 – 250 °C (10 °C/min),
curing condition ; 125 °C × 1 hr

TMA : SII TMA/SS6100 -55 – 150 °C (5 °C/min),
curing condition ; 125 °C × 1 hr

Thermal conductivity : C-Therm Tci, curing condition ; 125 °C × 1 hr

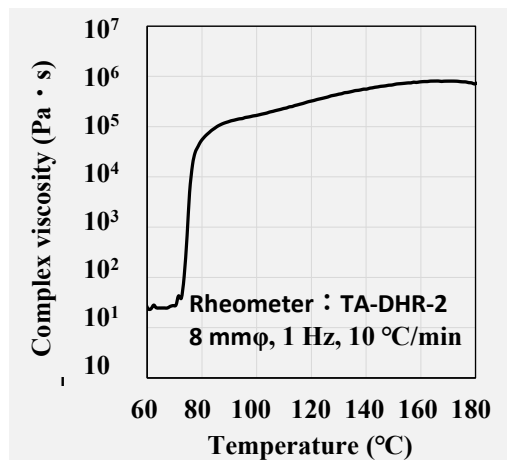
Recommended Curing Conditions

125 °C

1.0 hr

Lase curing condition (e.g.) : 940 nm, 4 mmφ, 3 W, 3 sec.

Curing behavior (Reference image)



Usage

【Storage】 Store frozen (below -20 °C)

【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.
Recommended defrosting time : Syringe ; 25 °C, 1 h or more.
Barrel ; 25 °C, 2 h or more.

【Curing】 When curing more than 1 g, please be careful of runaway reactions.

【Disposal】 Please refer to SDS for proper treatment.

【Others】 Please contact us at the following

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